

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10593152			
<b>Filing Date:</b>	18-Sep-2006			
<b>Title of Invention:</b>	ELECTRODEPOSITED COPPER FOIL WITH CARRIER FOIL ON WHICH A RESIN LAYER FOR FORMING INSULATING LAYER IS FORMED, COPPER-CLAD LAMINATE, PRINTED WIRING BOARD, METHOD FOR MANUFACTURING MULTILAYER COPPER-CLAD LAMINATE, AND METHOD FOR MANUFACTURING PRINTED WIRING BOARD			
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<b>Attorney Docket Number:</b>	3209-124			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1510	1510
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1810